

NTC

Product Class	NTC SMD B57xxxC5* (without inner electrode) 07.10.2019							
Date								
IMDS ID if available								
Version	5.07							
Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS**) [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)	
Active Part	Ceramic	3B	Mn3O4 NiO Co3O4 others*)	64 17 15 4	1317-35-7 1313-99-1 1308-06-1	90		
Termination	Composite	4D	Ag Glass frit (boro-silicate)	94 6	7440-22-4	7.5		
	Heavy Metal	1C8	Sn	100	7440-31-5	1.5		
	Heavy Metal	1C14	Ni	100	7440-02-0 Sum of total	1 100		
3.2 x 1.6 0.018 - 0.030 B57621C5103*			case size 1206 1206					
Contact	Ronner Christoph			Important remarks:				
Division	PPD Q QM			1) The decla	 The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces are 			
Address	8530 Deutschlandsberg, AUSTRIA			product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise				
	Tel: mailto: 2) This Material Data Sheet contains typical values of the respective products +43 3462 800 2139 functional.ppd-egpm.db@tdk-electronics.tdk.com herein. We expressly point out that all values and statements contained herein are							
*) others: .(not declarable or prohibited substances acc. GADSL) **) typical mass percentage of substance				best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.				
					quirements according to Art. 4 (es in electrical and electronic ec		Directive 2011/65/EU	
Image: Second	ead as an alloying element in sad as an alloying element in opper alloy containing up to sad in high melting temperat ectrical and electronic comp ad in dielectric ceramic in c sad in dielectric ceramic in c	a steel for machining purpose a aluminium containing up to 4 % lead by weight; ure type solder (i.e. lead-bas onents containing lead in a g apacitors for a rated voltage apacitors for a rated voltage viable electrical connection t	ed alloys containing 85 % by weight	up to 0,35 % lead by we or more lead); ceramic in capacitors, e.	.g. piezoelectronic devices, or in a gla	ass or ceramic matrix compoun	d;	